

HF RoHS TwinChip™ Series - DO-214

TwinChip Series

Description

TwinChip™ Series DO-214 are very low capacitance SIDACTor® devices designed to protect broadband equipment such as VoIP, DSL modems and DSLAMs from damaging overvoltage transients. This series provides a surface mount solution that enables equipment to comply with global regulatory standards, while limiting the impact to broadband signals.


Features and Benefits

- Low voltage overshoot
- Low on-state voltage
- Does not degrade with use
- Low distortion
- Fails short circuit when surged in excess of ratings
- 40% lower capacitance than comparable product

Applicable Global Standards

- TIA/968-A
- ITU K.20/21
- IEC 61000-4-5
- GR 1089 Intra-building
- YD/T 1082
- YD/T 993
- YD/T 950

Agency Approvals

Agency	Agency File Number
	E133083

Pinout Designation

NOT APPLICABLE

Schematic Symbol

Electrical Characteristics

Part Number	Marking	V_{DRM} @ $I_{DRM} = 5\mu A$	V_s @ $100V/\mu s$	I_H	I_s	I_T	V_T @ $I_T = 2.2$ Amps	Capacitance @ 1MHz, 2V bias	
		V min	V max	mA min	mA max	A max	V max	pF min	pF max
P0642SALRP	P062A	58	77	120	800	2.2	8	25	45
P0722SALRP	P072A	65	88	120	800	2.2	8	20	45
P0902SALRP	P092A	75	98	120	800	2.2	8	20	40
P1102SALRP	P112A	90	130	120	800	2.2	8	15	35
P1302SALRP	P132A	120	160	120	800	2.2	8	15	35
P1502SALRP	P152A	140	180	120	800	2.2	8	15	30
P1802SALRP	P182A	170	220	120	800	2.2	8	10	30
P2302SALRP	P232A	190	260	120	800	2.2	8	10	25
P2602SALRP	P262A	220	300	120	800	2.2	8	10	25
P3002SALRP	P302A	280	360	120	800	2.2	8	10	25
P3502SALRP	P352A	320	400	120	800	2.2	8	10	20
P4202SALRP	P422A	380	500	120	800	2.2	8	10	20
P4802SALRP	P482A	440	600	120	800	2.2	8	5	20
P6002SALRP	P602A	550	700	120	800	2.2	8	5	20

Table continues on next page.

Electrical Characteristics (continued)

Part Number	Marking	V_{DRM} @ $I_{DRM}=5\mu A$	V_S @ 100V/ μs	I_H	I_S	I_T	V_T @ $I_T=2.2 A$	Capacitance @ 1MHz, 2V bias	
		V min	V max	mA min	mA max	A max	V max	pF min	pF max
P0642SBLRP	P062B	58	77	120	800	2.2	8	25	45
P0722SBLRP	P072B	65	88	120	800	2.2	8	20	45
P0902SBLRP	P092B	75	98	120	800	2.2	8	20	40
P1102SBLRP	P112B	90	130	120	800	2.2	8	15	35
P1302SBLRP	P132B	120	160	120	800	2.2	8	15	35
P1502SBLRP	P152B	140	180	120	800	2.2	8	15	30
P1802SBLRP	P182B	170	220	120	800	2.2	8	10	30
P2302SBLRP	P232B	190	260	120	800	2.2	8	10	25
P2602SBLRP	P262B	220	300	120	800	2.2	8	10	25
P3002SBLRP	P302B	280	360	120	800	2.2	8	10	25
P3502SBLRP	P352B	320	400	120	800	2.2	8	10	20
P4202SBLRP	P422B	380	500	120	800	2.2	8	10	20
P4802SBLRP	P482B	440	600	120	800	2.2	8	5	20
P6002SBLRP	P602B	550	700	120	800	2.2	8	5	20

Notes:

- Absolute maximum ratings measured at $T_J=25^\circ C$ (unless otherwise noted).
- Devices are bi-directional (unless otherwise noted).

Surge Ratings

Series	I_{PP}									I_{TSM} 50/60 Hz	di/dt A/ μs
	0.2x310 ¹ 0.5x700 ²	2x10 ¹ 2x10 ²	8x20 ¹ 1.2x50 ²	10x160 ¹ 10x160 ²	10x560 ¹ 10x560 ²	5x320 ¹ 9x720 ²	10x360 ¹ 10x360 ²	10x1000 ¹ 10x1000 ²	5x310 ¹ 10x700 ²		
	A min	A min	A min	A min	A min	A min	A min	A min	A min		
A	20	150	150	90	50	75	75	45	75	20	500
B	25	250	250	150	100	100	125	80	100	25	500

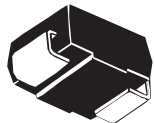
Notes:

 1 Current waveform in μs

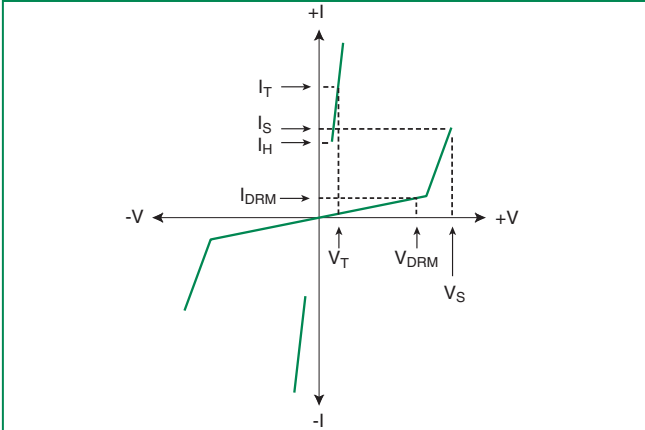
 2 Voltage waveform in μs

- Peak pulse current rating (I_{pp}) is repetitive and guaranteed for the life of the product.
- I_{pp} ratings applicable over temperature range of $-40^\circ C$ to $+85^\circ C$
- The device must initially be in thermal equilibrium with $-40^\circ C \leq T_J \leq +150^\circ C$

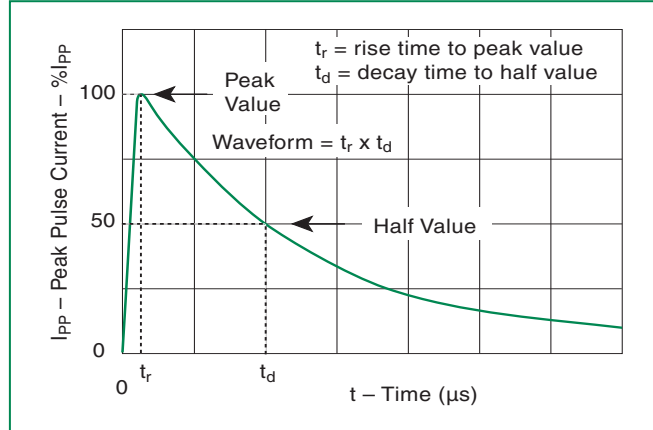
Thermal Considerations

Package	Symbol	Parameter	Value	Unit
DO-214AA 	T_J	Operating Junction Temperature Range	-40 to +150	$^\circ C$
	T_S	Storage Temperature Range	-65 to +150	$^\circ C$
	$R_{\theta JA}$	Thermal Resistance: Junction to Ambient	90	$^\circ C/W$

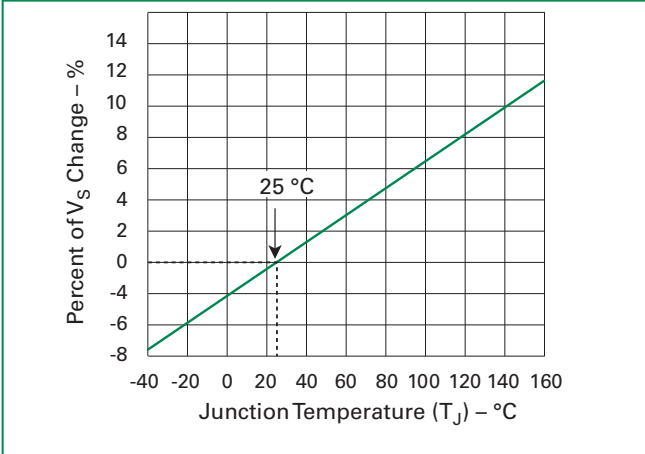
V-I Characteristics



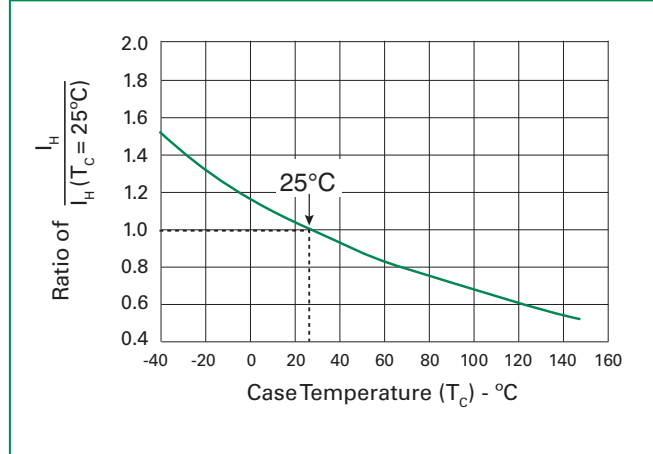
$t_r \times t_d$ Pulse Waveform



Normalized V_S Change vs. Junction Temperature

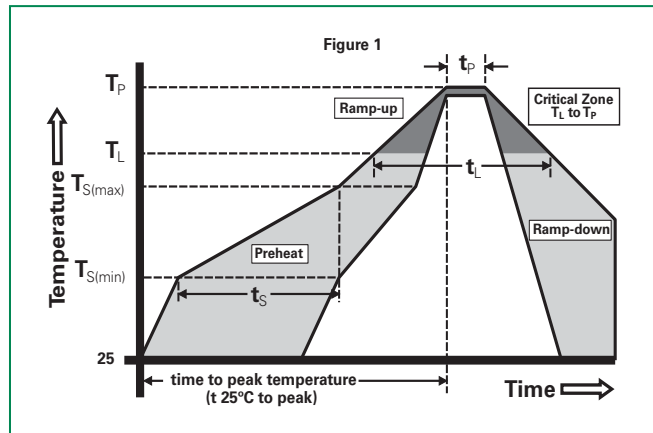


Normalized DC Holding Current vs. Case Temperature



Soldering Parameters

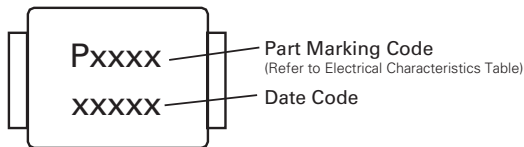
Reflow Condition		Pb-Free assembly (see Fig. 1)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max ($T_{s(max)}$)	+200°C
	-Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/sec. Max.
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max.
Reflow	-Temperature (T_L) (Liquidus)	+217°C
	-Temperature (t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)°C
Time within 5°C of actual PeakTemp (t_p)		30 secs. Max.
Ramp-down Rate		6°C/sec. Max.
Time 25°C to Peak Temp (T_p)		8 min. Max.
Do not exceed		+260°C



Physical Specifications

Lead Material	Copper Alloy
Terminal Finish	100% Matte-Tin Plated
Body Material	UL recognized epoxy meeting flammability classification 94V-0

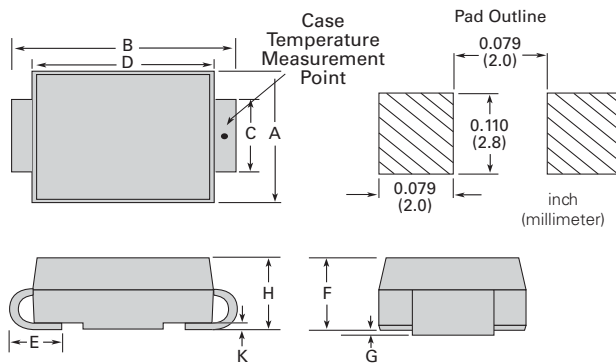
Part Marking



Environmental Specifications

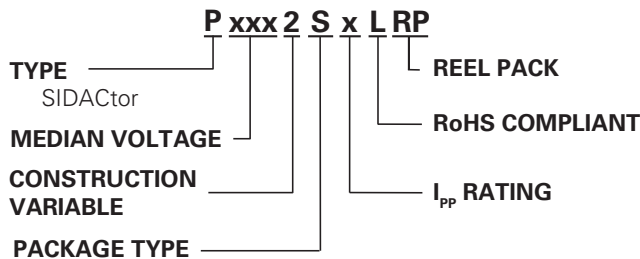
High Temp Voltage Blocking	80% Rated V_{DRM} ($V_{AC Peak}$) +125°C or +150°C, 504 or 1008 hrs. MIL-STD-750 (Method 1040) JEDEC, JESD22-A-101
Temp Cycling	-65°C to +150°C, 15 min. dwell, 10 up to 100 cycles. MIL-STD-750 (Method 1051) EIA/JEDEC, JESD22-A-104
Biased Temp & Humidity	52 V_{DC} (+85°C) 85%RH, 504 up to 1008 hrs. EIA/JEDEC, JESD22-A-101
High Temp Storage	+150°C 1008 hrs. MIL-STD-750 (Method 1031) JEDEC, JESD22-A-101
Low Temp Storage	-65°C, 1008 hrs.
Thermal Shock	0°C to +100°C, 5 min. dwell, 10 sec. transfer, 10 cycles. MIL-STD-750 (Method 1056) JEDEC, JESD22-A-106
Autoclave (Pressure Cooker Test)	+121°C, 100%RH, 2atm, 24 up to 168 hrs. EIA/JEDEC, JESD22-A-102
Resistance to Solder Heat	+260°C, 30 secs. MIL-STD-750 (Method 2031)
Moisture Sensitivity Level	85%RH, +85°C, 168 hrs., 3 reflow cycles (+260°C Peak). JEDEC-J-STD-020, Level 1

Dimensions – DO-214AA



Dimensions	Inches		Millimeters	
	Min	Max	Min	Max
A	0.130	0.156	3.30	3.95
B	0.201	0.220	5.10	5.60
C	0.077	0.087	1.95	2.20
D	0.159	0.181	4.05	4.60
E	0.030	0.063	0.75	1.60
F	0.075	0.096	1.90	2.45
G	0.002	0.008	0.05	0.20
H	0.077	0.104	1.95	2.65
K	0.006	0.016	0.15	0.41

Part Numbering



Packing Options

Package Type	Description	Quantity	Added Suffix	Industry Standard
S	DO-214AA Tape & Reel	2500	RP	EIA-481-D

Tape and Reel Specification — DO-214AA

